

<u>Sensor production</u> <u>readiness</u>

G. Bolla, Purdue University for the USCMS FPIX group

PMG review 02/25/2005

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<u>Outline</u>

Sensor requirements Geometry Radiation hardness • Development Guard Rings P-stops • The final design (performance) Laser measurements (CCE) FNAL test beam results CERN test beam results Conclusions



<u>Sensor requirements</u> Geometrv

- Pitches are set by the ROC design
 - 150 μm x 100 μm pitch
 - 100-200 x 100 bonding pitch
- Dimensions are set by the blade design
 - 7 different sensors are needed for a blade
 - <u>5 different geometries</u>





Sensor geometry	Active area X [µm]	Active area Y [µm]	Edge to Edge X [µm]	Edge to Edge Υ [μm]
2x1	16200	8100	18594	10494
3x2	24300	16200	26694	18594
4x2	32400	16200	34794	18594
5x2	40500	8100	42894	18594
5x1	40500	16200	42894	10494

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<u>HV operations</u> <u>Guard Rings</u>

Finalized in 1999 with the engineering run
 PSI-JHU-PURDUE-BTeV

- Two vendors
 - Sintef
 - CSEM (later Colibris later out of business)
- Vdep ~ 180-200 V
- 10+1 Guard-rings add ~1.2 mm on each edge of the sensor
 - Holds >1000V before irradiation
 - Holds >800V after 6 10¹⁴



Nucl.Instrum.Meth.A461:182-184,2001



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HV operations

<u>p-stops</u>

- P-stops edges are the points with high electric field
 - Shapes and distances strongly affects the maximum HV reachable







Nucl.Instrum.Meth.A501:160-163,2003

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F and FM design

2001: submission with Sintef with

- Only 2 design left for large sensors
 - PSI30 Honeywell (irradiated and bumped at PSI)
 - PSI43 DMILL (bumped at MCNC and IZM)
 - PSI46 ¼ µm (bumped at IZM and VTT)





- Assembly experience
- CCE measurements
- Test beam



<u>P-stops geometry and</u> <u>CCE (Charge Collection Efficiency)</u>

 1064 nm laser (goes through more than 300 μm of Si)

- Beam size ~10 μm
- Scans in $\geq 2 \mu m$ steps
- Technique allows:
 - One to one comparison on the CCE performance of the 2 design (F and FM).
 - Dependence on Vbias



Implanted n+ pixel (also metalized) ~98 µm square

P-stops ring 8 μm wide with 12 μm gaps

Metal grid on the p-side

Contact between the Al and the n+ implanted pixel





direct comparison

F design at 320 V

The Compact Muon Solenoid

FM design at 320 V







FM design at 250 V

FM design at 350 V



The decision to move to a higher resistivity (90-100 V depletion on diodes versus the 180-200 V of the 2001 submission) allows for more over depletion to be applied and so better CCE (lower inefficiencies) in the corner regions.









FNAL Test beam

Beam telescope

•8 strip planes(4X + 4Y)
•1 plane = 2 ROC's = 2 x 128 ch
•Strips pitch : 50um



single cluster is used for tracking
alignment variables : theta, offset
track_residual < 3um





FNAL Test beam

Months of data taking with the DMILL PSI43

 Unstable performance

 12/20/04 switched to ¼ µm PSI46v1

 Reliable operation and robust efficiency measurements
 No charge information: a binary chip

Pixel detector

Sensor design : FM
4160 pixels/ROC
Chip : PSI46v1, 1x2 chip

→ 1 chip has 52 columns and 80 rows
→ 8.1 mm x 8.1 mm
→ No charge information

Pixel size : 150um(col) x 100um(row)





<u>Data set</u>

Not tilted

run	Bias Volt.	Data Size
2635*	-350	250k
2643	-250	250k
2644	-400	250k
2645	-300	250k
2646	-200	250k
2648	-250	250k
2649*	-350	250k
2650*	-350	250k
2653*	-350	250k

Tilt 20 degree

run	Bias Volt.	Data Size
2663	-350	250k
2665	-300	250k
2666	-250	250k
2667	-200	250k
2668	-400	250k
2669	-350	250k

Runs with the * have been combined to get a high statistic sample





Number listed here for the 1M evts (4 runs combined)

Cut	Number of events	System/Sensor efficiency
	~ 1M	
Single track from the telescope	699299	30% have multiple tracks
Track quality	483700	15% with single tracks have poor track resolution
Pointing to the pixel array	309534	18 % are pointing outside of the pixel array
BAD TBM trailer	306263	A small percentage have DAQ troubles
Find pixel hits	304990	99.6 ± 0.3 %
Trk-pixel residual	304022	99.3 ± 0.3 %

CMS <u>No tilt Efficiency: 99.3 ± 0.3 %</u>

The Compact Muon Solenoid





100um (Row

Inefficiency is dominant at the corner of 4 pixelsConsistent with the laser results

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CMS <u>Rotation: 0° vs 20°</u>

Bias Voltage	# of Events	Good trk	Good hits	Efficiency
-200	250k	70348	68002	96.7 %
	250k	74938	73005	97.4 %
-250	250k	76221	75553	99.1 %
	250k	75618	75013	99.2 %
-300	250k	70868	70394	99.3 %
	250k	71511	71046	99.3 %
-350	1M	306263	304022	99.3 %
	250k	76304	75820	99.4 %
-400	_250k	70370	69185	99.5 %
	250k	73734	73310	99.4 %



CMS Post irradiation: CERN

CERN test beam data from fall 2004 Different ROC PSI30 (Honeywell from late 90s) Different pitch 125μm x 125 μm Analog charge available Threshold-less Pre-bump irradiation at CERN (6 10¹⁴) Bumped at PSI (indium) Single die metallurgy Many un-bonded pixels Post irradiation efficiency measurements





Illumination



Sensor	Bias Volt.	Dose	# of
		1 1	events
~~~~			
F	-300	Unirradiated	1424700
FM	-450	6 10 ¹⁴	1400000
FM	-600	6 10 ¹⁴	1040000

No un-irradiated FM design to be compared with the results from FNAL





### <u>measurements</u>





## <u>Other results</u>

- Signal to noise ratio of ~44 post 6 10¹⁴ irradiation (~45 for the p-spray as a comparison)
- No evidences of micro-discharges up to 600 V on irradiated device
  - True also around un-bonded pixels





## <u>Conclusions</u>

- Sensors for the CMS FPIX project have been developed.
- The geometry is driven by the other components of the system
- High voltage operation are guaranteed according to the TDR specification
- The particle detection efficiency is > 99% before any irradiation and after 6x10¹⁴ is still above 97 %
- The designed sensors are fully compatible with the goals of the project
- Daniela will present the results from the preproduction run